

AMENDMENTS TO THE CLAIMS:

Claims 1-12 (cancelled)

13. (New) A method for mounting a component, comprising:

recognizing a bad mark indicated on a circuit-formed substrate when individual substrates, provided by sectioning said circuit-formed substrate, include at least one defective individual substrate;

recognizing an individual substrate mark, provided on said circuit-formed substrate, so as to recognize a position and inclination of said individual substrates; and then

mounting a component on one of said individual substrates other than said at least one defective individual substrate,

wherein said bad mark is indicated on said individual substrate mark.

14. (New) A method for mounting a component, comprising:

recognizing a condition of a component after said component has been fed by a component-feeding device, sucked and removed from said component-feeding device, and while said component remains sucked, thereby providing a recognized condition of said component;

recognizing a condition of a circuit-formed substrate which is supported, regulated and secured, thereby providing a recognized condition of said circuit-formed substrate;

using a mark on at least one individual substrate, provided by sectioning said circuit-formed substrate, to recognize a position and inclination of said at least one individual substrate, thereby providing a recognized position and inclination of said at least one individual substrate;

calculating correctional amounts for a position and inclination of said component based on said recognized condition of said component, said recognized condition of said circuit-formed substrate, and said recognized position and inclination of said at least one individual substrate, thereby providing calculated correctional amounts;

performing any necessary correction of said component based on said calculated correctional amounts; and then

if said mark is recognized as a good mark, mounting said component at a predetermined position on said at least one individual substrate,

wherein a location of said mark on said at least one individual substrate is to be used as a location of a bad mark for identifying said at least one individual substrate as a defective individual substrate when said at least one individual substrate is judged as a defective individual substrate.

15. (New) The method according to claim 14, further comprising:

when said at least one individual substrate is judged as a defective individual substrate, indicating said bad mark by coloring said mark on said at least one individual substrate such that mounting of said component on said at least one individual substrate is not performed.

16. (New) A component-mounting apparatus comprising:

a component-feeding unit for feeding a component;

a mounting head for removing the component from said component-feeding unit, holding the component, and mounting the component onto a circuit-formed substrate;

a component-recognition camera for recognizing a condition of the component while held by said mounting head;

an X-Y robot for carrying said mounting head to a predetermined position;

a circuit-formed substrate-securing device for supporting and securing the circuit-formed substrate;

a substrate-recognition camera for recognizing a condition of the circuit-formed substrate when supported and secured by said circuit-formed substrate-securing device; and

a control unit for controlling overall operations of the apparatus such that

(i) said substrate-recognition camera recognizes an individual substrate mark provided on at least one individual substrate, provided by sectioning the circuit-formed substrate, so as to recognize a position and inclination of the at least one individual substrate;

(ii) correctional amounts for a position and inclination of the component are calculated based on the position and inclination of the at least one individual substrate as recognized by said substrate-recognition camera, the condition of the component while held by said mounting

head as recognized by said component-recognition camera, and the condition of the circuit-formed substrate when supported and secured by said circuit-formed substrate-securing device as recognized by said substrate-recognition camera, so as to make any necessary correction of the component, and

(iii) said mounting head is carried by said X-Y robot so as to mount the component at a predetermined position on the at least one individual substrate,

wherein said substrate recognition camera is also for recognizing a bad mark indicated on an individual substrate mark of a defective individual substrate, when the circuit-formed substrate includes the defective individual substrate, while recognizing the individual substrate mark of the defective individual substrate.